

Please replace the paragraph beginning at page 5, line 21, with the following rewritten paragraph:

- (10) The process according to any one of (1) to (3), wherein said conductor layer is formed by a dry plating method.

Please replace Table 2 beginning on line 9 of page 20 with the following Table 2:

[Table 2]

	Heating temp. (°C)	Peel strength (N/cm)
Ex. 2	170	4.2
	220	4.4
Comp. Ex. 2	no	1.8

IN THE CLAIMS:

Please cancel non-elected claims 14-16 without prejudice or disclaimer.